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The Best Quality!

The Best Service!

Advanced People's Technology

Apple T

www.aplt.co.kr

Business Line

Apple T

01 ACT/MARK Tool Refurbishment & Service

02 Retrofit & Repair Service

03 R&D Solution

04 IDI-Cybor Pump Distribution

05 System Development

History

2023 ADMS Development Completed

2022. Jan Apple T New Company Building Completed

2019. Sept Certified ISO14001 & ISO45001

2016. Nov Apple T 2nd US Office Open in Dallas, Texas

2016. Jan Total Refurbished Tool Installationcount 100 System

2015. Nov Apple T US Office Open

2014. Aug Registered Co-Operation with SK Hynix

2009. Apr Certified ISO9001 & Korea Venture Entrepreneurship and INNOBI Association

2009. June First International Installation in X company Malaysia

2010. Apr Registered Co-Operation with Dongbu HiTek

2008. Oct Registered 2 Patents of Semiconductor System

2006. Apr Registered Co-Operation with Samsung

2005. Mar Registered Co-Operation with Magnachip

2004.Jun Established Apple T Company

01.
ACT8/ACT12 Refurbishment and Modification







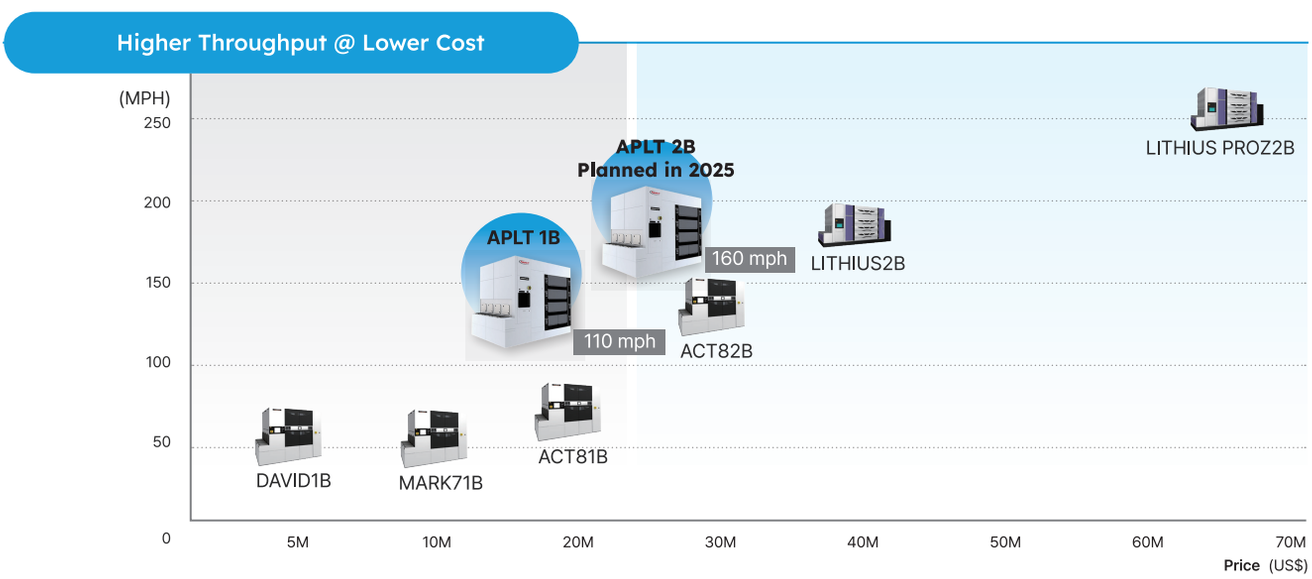


Hardware Modification	Software Correspondence according to Hardware Modification
• Spin unit Modification and Using Alternation	• Add Pump of Coater unit (0 pump·4 Pumps)
• Chemical Supply Modification	• Change from oven unit (eg·CHP)
• Modify Coat unit (SOG·Normal Coat)	• Add HHP & LHP unit
• Add Resist Pump & Nozzle (2Nozzle·4Nozzle)	• Change from oven unit (LHP·CPL)
• Add Hot plate + Cool plate	• Modify Interface type (SVG·ASML)
• Modify WEE unit (Wafer Type NOTCH·FLAT ZONE)	• Chemical Supply
• PRA or IRA TRANSFER MOVING SPEED UP-GRADE - PRA : X1,2,3,Z-axis (Motor & Driver) - IRA : X-axis (Motor & Driver Change)	• Modify Configuration & Wafer Flow (R/L) Type

02.
AppleT Track System SPEED-200iS



SPECIFICATION	DESCRIPTION
Model	SPEED200iS
Wafer Size	200mm, 150mm
	4 STAGE OPEN CASSETTE TYPE
	6 SPINNERS
Hardware	16 PLATES
	2 TRANSITION(CSB, IFB)
	IFB(2*WEE)/INLINE, LOCAL
Size	2310W*1550D*2620H
Throughput	Sigle Block: 110 MPH Dual Block: 160 MPH



Change of Market	Used Equipment BIZ	Securing Global Customers	Engineering
Competitive price and delivery date	Used Equipment Prices Surge	Securing Major Domestic/Foreign Semiconductor Customers	Refurbishment Technology since 2004
150/200mm Foundry Market's Diverse Needs	OEM Parts Discontinuance & Obsoleteness	Sales Networks in the U.S., Europe, etc.	Ensuring equipment design and structural analysis capabilities
Growth of Power IC Markets (SiC, GaN)	Lack of Core Tool (China's Investment Expansion)		Used Equipment Prices Surge

03.
AppleT Defect Monitoring System ADMS

Inline Defect Monitoring system incorporating Apple T's New **IMAGE SENSOR** and **A.I.SOFTWARE** in the TRACK
Maximize quality improvement, cost reduction, and productivity by instantly detecting, analyzing, and taking actions against various MACRO defects

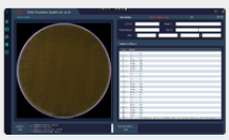
01. APPLE T IMAGE SENSOR





02. ADMS SYSTEM

Defect type analysis



ADMS and FAB HOST communication
Report OK or NG judgment to HOST by category

03. ADMS SERVER (OPTION)



FAB MES(ON LINE HOST)

Considering the process environment,
set the INTERLOCK condition in the HOST and use it

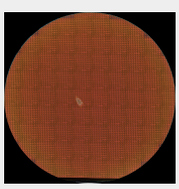
- LOT HOLD condition setting
- TOOL DOWN condition setting

04. ENGINEER

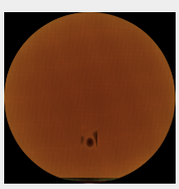


Maximizing efficiency through further defect analysis

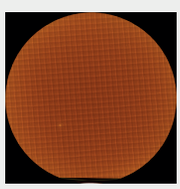
- Root Cause analysis
- Improved preventive maintenance intervals
- Yield Improvement
- AI Deep Learning



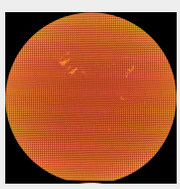
CHEMICAL DROP



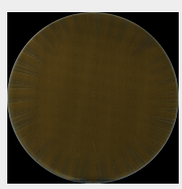
DEFOCUS



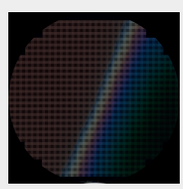
PARTICLE



SCRATCH



COATING FAIL

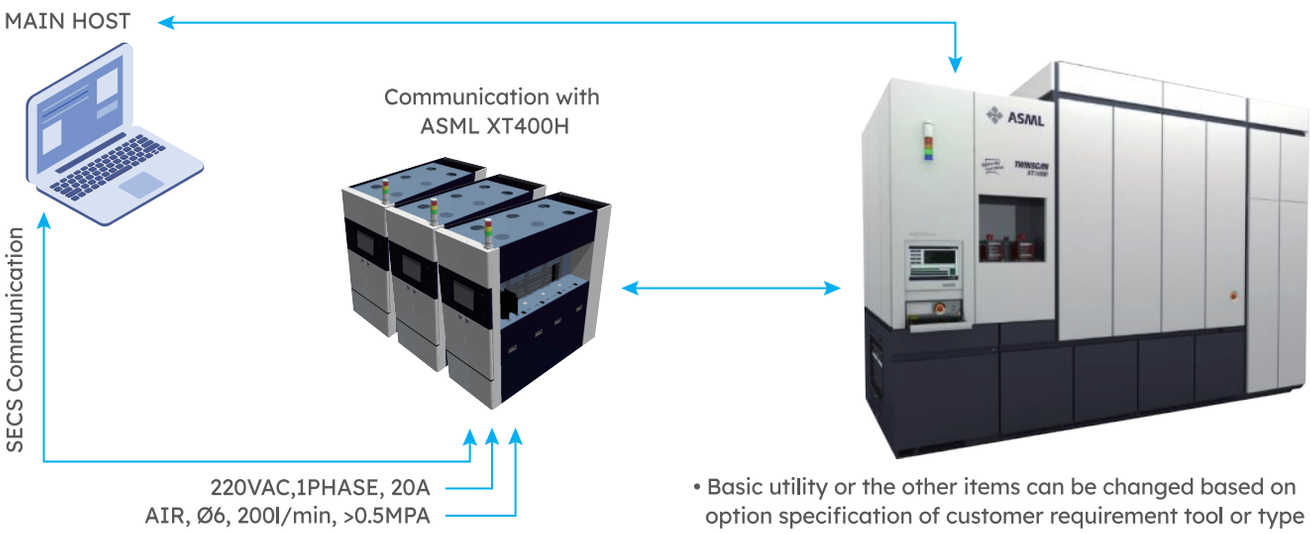


WAFER TILT

ADMS Specification

Category		Size	Comments
Small Defect	Particle	45㎛ ~ 150㎛	NG/OK, Category Name, Defect Count, Coordinate
Middle Defect	Particle	150㎛ ↑	
	Scratch		
	Defocus		
	Burst		
	Edge Chip		
Large Defect	Coating Defect	N.A.	NG/OK, Category Name
	Develop Defect		
	DI Rinse Defect		
	Bake Tilt Defect		
EBR/WEE	Width	Spec ± 0.05 mm	7 pts. excluding Flat zone, Notch

04.
AppleT Loader System(EFEM)



• Basic utility or the other items can be changed based on option specification of customer requirement tool or type

- Interface with ASML XT400H
- Ceramic single pincette
- CE and SEMI approved

	ATLS-200	ATLS-200S	ATLS-300
Wafer size	200mm	200mm	300mm
Carrier	OPEN	SMIF	FOUP
PORT	4	4	4
Throughput	250 WPH	250 WPH	200 WPH

05.
IDI-Cybor M650 pump

Exclusive Distributor for products of Teledyne Integrated Designs



- Roling Diaphragm w/Stepper motor
- No hydraulic Fluid
- Dispense volume : 0.1 - 20ml
- Viscosity : Max 50,000cp
- Purge Volume : 60ml/Cycle
- On Board controller
- CE certified

06.
Research Development Process & Strategy

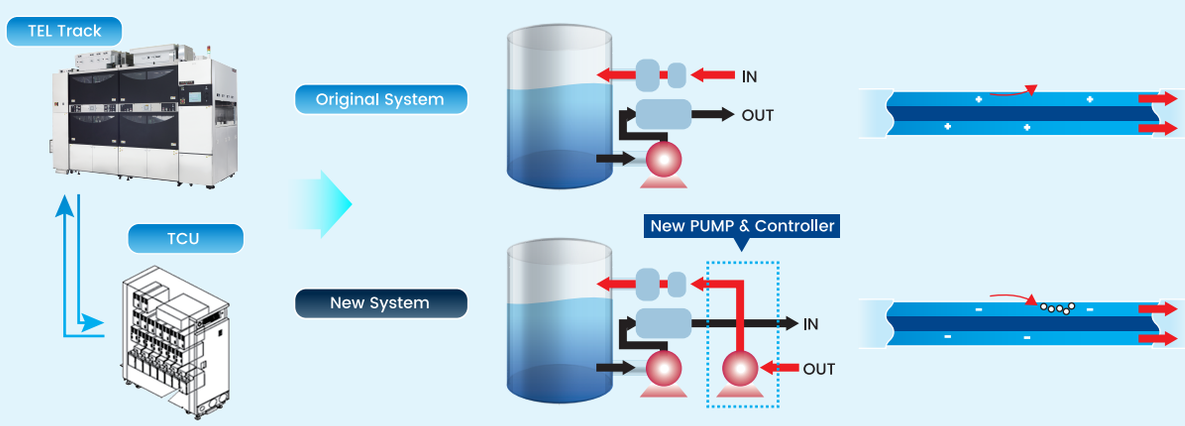
We continue seek for solutions!

The main purpose of R&D process is to provide solution of the customers' inconvinience on the current systems.
Apple T approaches towards the current problems or Customer's improvement will by working directly with end users.

Customers can either select from current available solutions that Apple T already have or work with Apple T R&D team to develop new solution items.

Current Problems or Improvement Will ▸ Inquiry to Apple Team (Sales or R&D team) ▸ Specific discussion and information exchanged ▸ Customer evaluate and decision of selection to be made ▸ R&D team and Engineering team develop or select from current available items

07.
System Improvement - Water leakage protection system



Water leakage protection system

- No water dripping on the wafer with negative water pressure
- Easy to detect the leakage of Temp Controlled Water line
- Application: MK7, ACT8 & ACT12